

## Features:

- Aluminium metal-base copper-clad laminate PCB
- Design for Xeon 3 Power Series LED
- Base metal is 1.5mm Aluminium
- With HTCD Thermally Conductive Dielectric to suitable high power LED
- Copper Circuit Foil is 35µ m(1oz)
- Surface Finish is White Solder Mask, Pb-free HASL solder pads (RoHS compliant)

## Applications

- Used for Xeon 3 Power Series, eg: OSW4XME1C1E

## Appendix

### Data and information for MCPCB

Items	Unit	Reference
Thermal Conductivity	W/mK	0.8W/mK
Dielectric thickness	µm	100
Breakdown voltage	kV(DC)	> 3kV
Insulation resistance	Ω	10 <sup>5</sup>
Maximum Working Temperature	°C	130
Peel Strength	N/mm	> 1.4
Blistering after heat shock within 1 minutes	°C	<260
Copper thickness	µm	35
Base metal plate	-	Aluminium
Base metal thickness	mm	1.5

